

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2977667

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	YI-TING WANG	08/06/2014
	CHIA-YING LIN	08/07/2014
	RUN-CI GAO	08/04/2014
	HUNG-HAN LIN	08/04/2014
	CHIA-CHI HO	08/04/2014
	CHUNG-SHI CHIANG	08/04/2014
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED	
Street Address:	NO. 8, LI-HSIN ROAD 6	
Internal Address:	HSIN-CHU SCIENCE PARK	
City:	HSIN-CHU	
State/Country:	TAIWAN	
Postal Code:	300-77	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	14457357
CORRESPONDENCE DATA		
Fax Number:		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	2166540090	
Email:	jcarpenter@cooperlegalgroup.com	
Correspondent Name:	COOPER LEGAL GROUP LLC	
Address Line 1:	6505 ROCKSIDE ROAD SUITE 330	
Address Line 4:	INDEPENDENCE, OHIO 44131	
ATTORNEY DOCKET NUMBER:	TSMC2014-0076	
NAME OF SUBMITTER:	MARCUS A. FISCHER	
SIGNATURE:	/Marcus A. Fischer/	
DATE SIGNED:	08/12/2014	
Total Attachments: 3		

PATENT

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ASSIGNMENT

For good and valuable consideration received of the hereinafter named assignee, receipt of which is hereby acknowledged, the undersigned


Yi-Ting Wang Zhubei City, TW	Chia-Ying Lin Tainan City, TW	Run-Ci Gao Hukou Township, TW
Hung-Han Lin Hsinchu city, TW	Chia-Chi Ho Zhudong Township, TW	Chung-Shi Chiang Zhubei City, TW

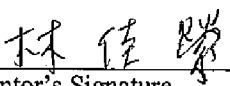
NOW, THEREFORE, for and in consideration of our employment and the salary or wages paid to us by Taiwan Semiconductor Manufacturing Company Limited, I/we, Yi-Ting Wang, Chia-Ying Lin, Run-Ci Gao, Hung-Han Lin, Chia-Chi Ho, Chung-Shi Chiang, by these presents do sell, assign, and transfer unto said Taiwan Semiconductor Manufacturing Company Limited, a corporation organized and existing under the laws of the Republic of China, having its principal place of business at No. 8, Li-Hsin Road 6, Hsin-Chu Science Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring an interest therein, its successors and assigns, the entire right, title and interest, so far as concerns the United States and the Territories and Possessions thereof and all foreign countries, in and to the inventions entitled

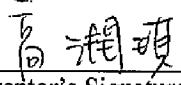
CIRCUIT ARRANGEMENT FOR MODELING

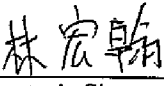
for which application for United States Letters Patent has been filed on _____ under Serial No. _____, or was executed by the undersigned on the date below and is being filed concurrently herewith, said application for United States Letters Patent, any and all other applications for Letters Patent on said inventions in countries foreign to the United States, including all divisional, renewal, substitute, continuation and Convention applications based in whole or in part upon said inventions or upon said applications, and any and all Letters Patent and reissues and extensions of Letters Patent granted for said inventions or upon said applications, and every priority right that is or may be predicated upon or arise from said inventions, said applications and said Letters Patent; said assignee being hereby authorized to file patent applications in any or all countries on any or all said inventions in the name of the undersigned or in the name of said assignee or otherwise as said assignee may deem advisable, under the International Convention or otherwise; the Commissioner of Patents and Trademarks of the United States of America and the empowered officials of all other governments being hereby authorized to issue or transfer all said Letters Patent to said assignee in accordance herewith; this assignment being under covenant, not only that full power to make the same is had by the undersigned, but also that such assigned right is not encumbered by any grant, license, or other right heretofore given, and that the undersigned will do all acts reasonably serving to assure that said inventions, patent applications and Letters Patent shall be held and enjoyed by said assignee as fully and entirely as

the same could have been held and enjoyed by the undersigned if this assignment had not been made, and particularly to execute and deliver to said assignee all lawful documents including petitions, specifications, oaths, assignments, invention disclaimers, and lawful affidavits in form and substance which may be requested by said assignee, to furnish said assignee with all facts relating to said inventions or the history thereof and any and all documents, photographs, models, samples or other physical exhibits which may be useful for establishing the facts of conception, disclosure and reduction to practice of said inventions, and to testify in any proceedings relating to said inventions, patent applications and Letters Patent.

✓ 	✓ <u>2014.8.6.</u>
Inventor's Signature	Date
<u>Yi-Ting Wang</u>	
Printed Name in English	

✓ 	✓ <u>2014.8.7</u>
Inventor's Signature	Date
<u>Chia-Ying Lin</u>	
Printed Name in English	

✓ 	✓ <u>2014.8.4</u>
Inventor's Signature	Date
<u>Run-Ci Gao</u>	
Printed Name in English	

✓ 	✓ <u>2014.8.4</u>
Inventor's Signature	Date
<u>Hung-Han Lin</u>	
Printed Name in English	

✓ <u>何子奇</u>	✓ <u>2014.8.4</u>
Inventor's Signature	Date
<u>Chia-Chi Ho</u>	
Printed Name in English	

✓ <u>江士昌</u>	✓ <u>2014.8.4</u>
Inventor's Signature	Date
<u>Chung-Shi Chiang</u>	
Printed Name in English	